



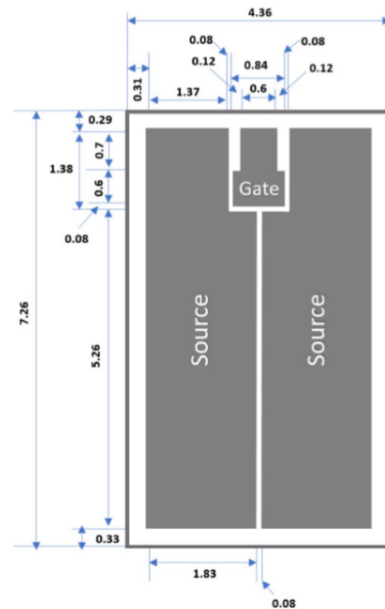
SemiDice

Wafer & Die Products

| | |
|--------------------------|--|
| Wafer/Die Part Number | CPM3-1200-0013A |
| Manufacturer | CREE |
| Dimensions (L x W x T) * | 286 mils x 172 mils 7.08 mils ±10% mils Thickness |
| Top Metal | Al 40k Å thickness |
| Back Metal | Ni/Au (8k/1k) Å thickness |



sample die



***MFG Tolerance not specified.**

The data contained herein is supplied for information only and is believed to be correct at the time of publication. These devices may change, without prior notification from SemiDice. SemiDice cannot accept any liability for the content. The customer is advised to verify device pad coordinates prior to ordering or shipment.

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